

Global Wafer-Level Underfill Market Growth 2026-2032

<https://marketpublishers.com/r/GB3A6C03420EEN.html>

Date: May 2026

Pages: 116

Price: US\$ 3,660.00 (Single User License)

ID: GB3A6C03420EEN

Abstracts

The global Wafer-Level Underfill market size is predicted to grow from US\$ 225 million in 2025 to US\$ 514 million in 2032; it is expected to grow at a CAGR of 12.4% from 2026 to 2032.

Wafer-level underfill is a high-reliability insulating encapsulation material used in wafer-level chip scale packaging, fan-in wafer-level packaging, fan-out wafer-level packaging, and related advanced packaging processes. It is typically supplied as a one-component heat-curable epoxy system in liquid or low-viscosity form, and after cure it forms a cross-linked polymer network. Inorganic fillers and functional additives are often incorporated to optimize flow behavior, coefficient of thermal expansion, mechanical strength, warpage control, and long-term reliability. The material is generally used at the wafer level or in wafer-level chip scale package applications to fill micro-gaps between die, redistribution layers, bumps, and adjacent structures, thereby reinforcing solder joints and interconnects and improving drop performance, thermal cycling resistance, humidity bias stability, and long-term service reliability. Major application areas include wafer-level chip scale packages, fan-in wafer-level packages, fan-out wafer-level packages, selected heterogeneous integration structures, and high-density advanced packaging, with major production and application regions concentrated in Mainland China, Taiwan, Japan, South Korea, Southeast Asia, and selected high-end packaging material supply chains in North America and Europe.

In 2025, global wafer-level underfill production reached approximately 110 to 150 tons. Based on visible capacity expansion in wafer-level chip scale packaging and advanced packaging, rising demand from artificial intelligence and high-performance computing related advanced packages, and observable commercial positioning of high-reliability wafer-level underfill materials, the representative free-on-board price generally ranged from about US\$1,500 to US\$2,400 per kilogram in 2025.

The global wafer-level underfill market is rapidly evolving from a conventional packaging reliability support material into a critical functional material within advanced packaging and high-density interconnect systems. As artificial intelligence training and inference processors, high-bandwidth memory, chiplet architectures, and heterogeneous integration continue to scale, wafer-level and fan-out packages are moving toward higher routing density, larger package formats, and tighter warpage control requirements. This is directly raising material requirements for low voiding, low stress, high adhesion, low coefficient of thermal expansion, and high cleanliness. Henkel's official materials explicitly identify wafer-level chip scale packages as an underfill application and note that such materials can significantly improve drop performance and thermal cycle performance. Its advanced packaging materials guidance also indicates that certain wafer-level materials are applied directly in fan-in wafer-level packaging, fan-out wafer-level packaging, and heterogeneous integration scenarios. TSMC has repeatedly highlighted the importance of advanced packaging and 3D stacking technologies for artificial intelligence and high-performance computing, while also disclosing sustained strong demand for CoWoS, InFO, and related platforms. This means wafer-level underfill is increasingly becoming a key enabling material for advanced package success rather than merely a supporting assembly material.

From a commercial perspective, growth in wafer-level underfill is no longer limited to smartphones and thin consumer electronics. It is increasingly supported by high-performance computing, artificial intelligence accelerators, advanced memory packaging, and selected high-reliability automotive electronics. In finer-pitch, more highly integrated, and structurally complex wafer-level and fan-out packages, the material must deliver not only excellent gap-filling performance, but also a more precise balance among warpage control, thermal cycling reliability, humidity stability, and process compatibility. At the same time, the market faces clear constraints, including long customer qualification cycles, rising customization requirements driven by package structural diversity, and higher demands on process window control and batch-to-batch consistency in larger advanced packages. Future competition will increasingly center on advanced packaging compatibility, formulation and rheology control capability, automotive-grade and high-reliability qualification strength, and ecosystem alignment with leading foundries, outsourced assembly and test providers, and materials suppliers.

LP Information, Inc. (LPI) 's newest research report, the "Wafer-Level Underfill Industry Forecast" looks at past sales and reviews total world Wafer-Level Underfill sales in 2025, providing a comprehensive analysis by region and market sector of projected Wafer-Level Underfill sales for 2026 through 2032. With Wafer-Level Underfill sales

broken down by region, market sector and sub-sector, this report provides a detailed analysis in US\$ millions of the world Wafer-Level Underfill industry.

This Insight Report provides a comprehensive analysis of the global Wafer-Level Underfill landscape and highlights key trends related to product segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyzes the strategies of leading global companies with a focus on Wafer-Level Underfill portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms' unique position in an accelerating global Wafer-Level Underfill market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for Wafer-Level Underfill and breaks down the forecast by Type, by Application, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast offers a highly nuanced view of the current state and future trajectory in the global Wafer-Level Underfill.

This report presents a comprehensive overview, market shares, and growth opportunities of Wafer-Level Underfill market by product type, application, key manufacturers and key regions and countries.

Segmentation by Type:

Liquid Underfill

Paste Underfill

Film Underfill

Segmentation by Cure Profile:

Standard Thermal Cure

Fast Thermal Cure

Low Temperature Cure

Segmentation by Package Type:

Fan-Out Wafer-Level Packaging

Flip Chip Wafer-Level Packaging

3D Integrated Circuit Packaging

Others

Segmentation by Filler Type:

Nano-Filled

Silica-Filled

Others

Segmentation by Application:

Consumer Electronics

Data Center and Communications

Automotive Electronics

Others

This report also splits the market by region:

Americas

United States

Canada

Mexico

Brazil

APAC

China

Japan

Korea

Southeast Asia

India

Australia

Europe

Germany

France

UK

Italy

Russia

Middle East & Africa

Egypt

South Africa

Israel

Turkey

GCC Countries

The below companies that are profiled have been selected based on inputs gathered from primary experts and analysing the company's coverage, product portfolio, its market penetration.

Hubei Huitian New Materials Co., Ltd.

Darbond Technology Co., Ltd.

Jiangsu HHCK Advanced Materials Co., Ltd.

Henkel AG & Co. KGaA

Element Solutions Inc

NAMICS Corporation

Resonac Corporation

H.B. Fuller Company

Hoenle AG

Zymet, Inc.

Dexerials Corporation

Shin-Etsu Chemical Co., Ltd.

Key Questions Addressed in this Report

What is the 10-year outlook for the global Wafer-Level Underfill market?

What factors are driving Wafer-Level Underfill market growth, globally and by region?

Which technologies are poised for the fastest growth by market and region?

How do Wafer-Level Underfill market opportunities vary by end market size?

How does Wafer-Level Underfill break out by Type, by Application?

Contents

1 SCOPE OF THE REPORT

- 1.1 Market Introduction
- 1.2 Years Considered
- 1.3 Research Objectives
- 1.4 Market Research Methodology
- 1.5 Research Process and Data Source
- 1.6 Economic Indicators
- 1.7 Currency Considered
- 1.8 Market Estimation Caveats

2 EXECUTIVE SUMMARY

2.1 World Market Overview

- 2.1.1 Global Wafer-Level Underfill Annual Sales 2021-2032
- 2.1.2 World Current & Future Analysis for Wafer-Level Underfill by Geographic Region, 2021, 2025 & 2032
- 2.1.3 World Current & Future Analysis for Wafer-Level Underfill by Country/Region, 2021, 2025 & 2032

2.2 Wafer-Level Underfill Segment by Type

- 2.2.1 Liquid Underfill
- 2.2.2 Paste Underfill
- 2.2.3 Film Underfill
- 2.2.4 Wafer-Level Underfill Sales by Type
 - 2.2.4.1 Global Wafer-Level Underfill Sales Market Share by Type (2021-2026)
 - 2.2.4.2 Global Wafer-Level Underfill Revenue and Market Share by Type (2021-2026)
 - 2.2.4.3 Global Wafer-Level Underfill Sale Price by Type (2021-2026)

2.3 Wafer-Level Underfill Segment by Cure Profile

- 2.3.1 Standard Thermal Cure
- 2.3.2 Fast Thermal Cure
- 2.3.3 Low Temperature Cure
- 2.3.4 Wafer-Level Underfill Sales by Cure Profile
 - 2.3.4.1 Global Wafer-Level Underfill Sales Market Share by Cure Profile (2021-2026)
 - 2.3.4.2 Global Wafer-Level Underfill Revenue and Market Share by Cure Profile (2021-2026)
 - 2.3.4.3 Global Wafer-Level Underfill Sale Price by Cure Profile (2021-2026)

2.4 Wafer-Level Underfill Segment by Package Type

2.4.1 Fan-Out Wafer-Level Packaging

2.4.2 Flip Chip Wafer-Level Packaging

2.4.3 3D Integrated Circuit Packaging

2.4.4 Others

2.4.5 Wafer-Level Underfill Sales by Package Type

2.4.5.1 Global Wafer-Level Underfill Sales Market Share by Package Type
(2021-2026)

2.4.5.2 Global Wafer-Level Underfill Revenue and Market Share by Package Type
(2021-2026)

2.4.5.3 Global Wafer-Level Underfill Sale Price by Package Type (2021-2026)

2.5 Wafer-Level Underfill Segment by Filler Type

2.5.1 Nano-Filled

2.5.2 Silica-Filled

2.5.3 Others

2.5.4 Wafer-Level Underfill Sales by Filler Type

2.5.4.1 Global Wafer-Level Underfill Sales Market Share by Filler Type (2021-2026)

2.5.4.2 Global Wafer-Level Underfill Revenue and Market Share by Filler Type
(2021-2026)

2.5.4.3 Global Wafer-Level Underfill Sale Price by Filler Type (2021-2026)

2.6 Wafer-Level Underfill Segment by Application

2.6.1 Consumer Electronics

2.6.2 Data Center and Communications

2.6.3 Automotive Electronics

2.6.4 Others

2.6.5 Wafer-Level Underfill Sales by Application

2.6.5.1 Global Wafer-Level Underfill Sales Market Share by Application (2021-2026)

2.6.5.2 Global Wafer-Level Underfill Revenue and Market Share by Application
(2021-2026)

2.6.5.3 Global Wafer-Level Underfill Sale Price by Application (2021-2026)

3 GLOBAL BY COMPANY

3.1 Global Wafer-Level Underfill Breakdown Data by Company

3.1.1 Global Wafer-Level Underfill Annual Sales by Company (2021-2026)

3.1.2 Global Wafer-Level Underfill Sales Market Share by Company (2021-2026)

3.2 Global Wafer-Level Underfill Annual Revenue by Company (2021-2026)

3.2.1 Global Wafer-Level Underfill Revenue by Company (2021-2026)

3.2.2 Global Wafer-Level Underfill Revenue Market Share by Company (2021-2026)

- 3.3 Global Wafer-Level Underfill Sale Price by Company
- 3.4 Key Manufacturers Wafer-Level Underfill Producing Area Distribution, Sales Area, Product Type
 - 3.4.1 Key Manufacturers Wafer-Level Underfill Product Location Distribution
 - 3.4.2 Players Wafer-Level Underfill Products Offered
- 3.5 Market Concentration Rate Analysis
 - 3.5.1 Competition Landscape Analysis
 - 3.5.2 Concentration Ratio (CR3, CR5 and CR10) & (2024-2026)
- 3.6 New Products and Potential Entrants
- 3.7 Market M&A Activity & Strategy

4 WORLD HISTORIC REVIEW FOR WAFER-LEVEL UNDERFILL BY GEOGRAPHIC REGION

- 4.1 World Historic Wafer-Level Underfill Market Size by Geographic Region (2021-2026)
 - 4.1.1 Global Wafer-Level Underfill Annual Sales by Geographic Region (2021-2026)
 - 4.1.2 Global Wafer-Level Underfill Annual Revenue by Geographic Region (2021-2026)
- 4.2 World Historic Wafer-Level Underfill Market Size by Country/Region (2021-2026)
 - 4.2.1 Global Wafer-Level Underfill Annual Sales by Country/Region (2021-2026)
 - 4.2.2 Global Wafer-Level Underfill Annual Revenue by Country/Region (2021-2026)
- 4.3 Americas Wafer-Level Underfill Sales Growth
- 4.4 APAC Wafer-Level Underfill Sales Growth
- 4.5 Europe Wafer-Level Underfill Sales Growth
- 4.6 Middle East & Africa Wafer-Level Underfill Sales Growth

5 AMERICAS

- 5.1 Americas Wafer-Level Underfill Sales by Country
 - 5.1.1 Americas Wafer-Level Underfill Sales by Country (2021-2026)
 - 5.1.2 Americas Wafer-Level Underfill Revenue by Country (2021-2026)
- 5.2 Americas Wafer-Level Underfill Sales by Type (2021-2026)
- 5.3 Americas Wafer-Level Underfill Sales by Application (2021-2026)
- 5.4 United States
- 5.5 Canada
- 5.6 Mexico
- 5.7 Brazil

6 APAC

6.1 APAC Wafer-Level Underfill Sales by Region

6.1.1 APAC Wafer-Level Underfill Sales by Region (2021-2026)

6.1.2 APAC Wafer-Level Underfill Revenue by Region (2021-2026)

6.2 APAC Wafer-Level Underfill Sales by Type (2021-2026)

6.3 APAC Wafer-Level Underfill Sales by Application (2021-2026)

6.4 China

6.5 Japan

6.6 South Korea

6.7 Southeast Asia

6.8 India

6.9 Australia

6.10 China Taiwan

7 EUROPE

7.1 Europe Wafer-Level Underfill by Country

7.1.1 Europe Wafer-Level Underfill Sales by Country (2021-2026)

7.1.2 Europe Wafer-Level Underfill Revenue by Country (2021-2026)

7.2 Europe Wafer-Level Underfill Sales by Type (2021-2026)

7.3 Europe Wafer-Level Underfill Sales by Application (2021-2026)

7.4 Germany

7.5 France

7.6 UK

7.7 Italy

7.8 Russia

8 MIDDLE EAST & AFRICA

8.1 Middle East & Africa Wafer-Level Underfill by Country

8.1.1 Middle East & Africa Wafer-Level Underfill Sales by Country (2021-2026)

8.1.2 Middle East & Africa Wafer-Level Underfill Revenue by Country (2021-2026)

8.2 Middle East & Africa Wafer-Level Underfill Sales by Type (2021-2026)

8.3 Middle East & Africa Wafer-Level Underfill Sales by Application (2021-2026)

8.4 Egypt

8.5 South Africa

8.6 Israel

8.7 Turkey

8.8 GCC Countries

9 MARKET DRIVERS, CHALLENGES AND TRENDS

9.1 Market Drivers & Growth Opportunities

9.2 Market Challenges & Risks

9.3 Industry Trends

10 MANUFACTURING COST STRUCTURE ANALYSIS

10.1 Raw Material and Suppliers

10.2 Manufacturing Cost Structure Analysis of Wafer-Level Underfill

10.3 Manufacturing Process Analysis of Wafer-Level Underfill

10.4 Industry Chain Structure of Wafer-Level Underfill

11 MARKETING, DISTRIBUTORS AND CUSTOMER

11.1 Sales Channel

11.1.1 Direct Channels

11.1.2 Indirect Channels

11.2 Wafer-Level Underfill Distributors

11.3 Wafer-Level Underfill Customer

12 WORLD FORECAST REVIEW FOR WAFER-LEVEL UNDERFILL BY GEOGRAPHIC REGION

12.1 Global Wafer-Level Underfill Market Size Forecast by Region

12.1.1 Global Wafer-Level Underfill Forecast by Region (2027-2032)

12.1.2 Global Wafer-Level Underfill Annual Revenue Forecast by Region (2027-2032)

12.2 Americas Forecast by Country (2027-2032)

12.3 APAC Forecast by Region (2027-2032)

12.4 Europe Forecast by Country (2027-2032)

12.5 Middle East & Africa Forecast by Country (2027-2032)

12.6 Global Wafer-Level Underfill Forecast by Type (2027-2032)

12.7 Global Wafer-Level Underfill Forecast by Application (2027-2032)

13 KEY PLAYERS ANALYSIS

13.1 Hubei Huitian New Materials Co., Ltd.

- 13.1.1 Hubei Huitian New Materials Co., Ltd. Company Information
- 13.1.2 Hubei Huitian New Materials Co., Ltd. Wafer-Level Underfill Product Portfolios and Specifications
- 13.1.3 Hubei Huitian New Materials Co., Ltd. Wafer-Level Underfill Sales, Revenue, Price and Gross Margin (2021-2026)
- 13.1.4 Hubei Huitian New Materials Co., Ltd. Main Business Overview
- 13.1.5 Hubei Huitian New Materials Co., Ltd. Latest Developments
- 13.2 Darbond Technology Co., Ltd.
 - 13.2.1 Darbond Technology Co., Ltd. Company Information
 - 13.2.2 Darbond Technology Co., Ltd. Wafer-Level Underfill Product Portfolios and Specifications
 - 13.2.3 Darbond Technology Co., Ltd. Wafer-Level Underfill Sales, Revenue, Price and Gross Margin (2021-2026)
 - 13.2.4 Darbond Technology Co., Ltd. Main Business Overview
 - 13.2.5 Darbond Technology Co., Ltd. Latest Developments
- 13.3 Jiangsu HHCK Advanced Materials Co., Ltd.
 - 13.3.1 Jiangsu HHCK Advanced Materials Co., Ltd. Company Information
 - 13.3.2 Jiangsu HHCK Advanced Materials Co., Ltd. Wafer-Level Underfill Product Portfolios and Specifications
 - 13.3.3 Jiangsu HHCK Advanced Materials Co., Ltd. Wafer-Level Underfill Sales, Revenue, Price and Gross Margin (2021-2026)
 - 13.3.4 Jiangsu HHCK Advanced Materials Co., Ltd. Main Business Overview
 - 13.3.5 Jiangsu HHCK Advanced Materials Co., Ltd. Latest Developments
- 13.4 Henkel AG & Co. KGaA
 - 13.4.1 Henkel AG & Co. KGaA Company Information
 - 13.4.2 Henkel AG & Co. KGaA Wafer-Level Underfill Product Portfolios and Specifications
 - 13.4.3 Henkel AG & Co. KGaA Wafer-Level Underfill Sales, Revenue, Price and Gross Margin (2021-2026)
 - 13.4.4 Henkel AG & Co. KGaA Main Business Overview
 - 13.4.5 Henkel AG & Co. KGaA Latest Developments
- 13.5 Element Solutions Inc
 - 13.5.1 Element Solutions Inc Company Information
 - 13.5.2 Element Solutions Inc Wafer-Level Underfill Product Portfolios and Specifications
 - 13.5.3 Element Solutions Inc Wafer-Level Underfill Sales, Revenue, Price and Gross Margin (2021-2026)
 - 13.5.4 Element Solutions Inc Main Business Overview
 - 13.5.5 Element Solutions Inc Latest Developments

13.6 NAMICS Corporation

13.6.1 NAMICS Corporation Company Information

13.6.2 NAMICS Corporation Wafer-Level Underfill Product Portfolios and Specifications

13.6.3 NAMICS Corporation Wafer-Level Underfill Sales, Revenue, Price and Gross Margin (2021-2026)

13.6.4 NAMICS Corporation Main Business Overview

13.6.5 NAMICS Corporation Latest Developments

13.7 Resonac Corporation

13.7.1 Resonac Corporation Company Information

13.7.2 Resonac Corporation Wafer-Level Underfill Product Portfolios and Specifications

13.7.3 Resonac Corporation Wafer-Level Underfill Sales, Revenue, Price and Gross Margin (2021-2026)

13.7.4 Resonac Corporation Main Business Overview

13.7.5 Resonac Corporation Latest Developments

13.8 H.B. Fuller Company

13.8.1 H.B. Fuller Company Company Information

13.8.2 H.B. Fuller Company Wafer-Level Underfill Product Portfolios and Specifications

13.8.3 H.B. Fuller Company Wafer-Level Underfill Sales, Revenue, Price and Gross Margin (2021-2026)

13.8.4 H.B. Fuller Company Main Business Overview

13.8.5 H.B. Fuller Company Latest Developments

13.9 Hoenle AG

13.9.1 Hoenle AG Company Information

13.9.2 Hoenle AG Wafer-Level Underfill Product Portfolios and Specifications

13.9.3 Hoenle AG Wafer-Level Underfill Sales, Revenue, Price and Gross Margin (2021-2026)

13.9.4 Hoenle AG Main Business Overview

13.9.5 Hoenle AG Latest Developments

13.10 Zymet, Inc.

13.10.1 Zymet, Inc. Company Information

13.10.2 Zymet, Inc. Wafer-Level Underfill Product Portfolios and Specifications

13.10.3 Zymet, Inc. Wafer-Level Underfill Sales, Revenue, Price and Gross Margin (2021-2026)

13.10.4 Zymet, Inc. Main Business Overview

13.10.5 Zymet, Inc. Latest Developments

13.11 Dexerials Corporation

- 13.11.1 Dexerials Corporation Company Information
- 13.11.2 Dexerials Corporation Wafer-Level Underfill Product Portfolios and Specifications
- 13.11.3 Dexerials Corporation Wafer-Level Underfill Sales, Revenue, Price and Gross Margin (2021-2026)
- 13.11.4 Dexerials Corporation Main Business Overview
- 13.11.5 Dexerials Corporation Latest Developments
- 13.12 Shin-Etsu Chemical Co., Ltd.
- 13.12.1 Shin-Etsu Chemical Co., Ltd. Company Information
- 13.12.2 Shin-Etsu Chemical Co., Ltd. Wafer-Level Underfill Product Portfolios and Specifications
- 13.12.3 Shin-Etsu Chemical Co., Ltd. Wafer-Level Underfill Sales, Revenue, Price and Gross Margin (2021-2026)
- 13.12.4 Shin-Etsu Chemical Co., Ltd. Main Business Overview
- 13.12.5 Shin-Etsu Chemical Co., Ltd. Latest Developments

14 RESEARCH FINDINGS AND CONCLUSION

List Of Tables

LIST OF TABLES

- Table 1. Wafer-Level Underfill Annual Sales CAGR by Geographic Region (2021, 2025 & 2032) & (\$ millions)
- Table 2. Wafer-Level Underfill Annual Sales CAGR by Country/Region (2021, 2025 & 2032) & (\$ millions)
- Table 3. Major Players of Liquid Underfill
- Table 4. Major Players of Paste Underfill
- Table 5. Major Players of Film Underfill
- Table 6. Global Wafer-Level Underfill Sales by Type (2021-2026) & (Tons)
- Table 7. Global Wafer-Level Underfill Sales Market Share by Type (2021-2026)
- Table 8. Global Wafer-Level Underfill Revenue by Type (2021-2026) & (\$ million)
- Table 9. Global Wafer-Level Underfill Revenue Market Share by Type (2021-2026)
- Table 10. Global Wafer-Level Underfill Sale Price by Type (2021-2026) & (US\$/kg)
- Table 11. Major Players of Standard Thermal Cure
- Table 12. Major Players of Fast Thermal Cure
- Table 13. Major Players of Low Temperature Cure
- Table 14. Global Wafer-Level Underfill Sales by Cure Profile (2021-2026) & (Tons)
- Table 15. Global Wafer-Level Underfill Sales Market Share by Cure Profile (2021-2026)
- Table 16. Global Wafer-Level Underfill Revenue by Cure Profile (2021-2026) & (\$ million)
- Table 17. Global Wafer-Level Underfill Revenue Market Share by Cure Profile (2021-2026)
- Table 18. Global Wafer-Level Underfill Sale Price by Cure Profile (2021-2026) & (US\$/kg)
- Table 19. Major Players of Fan-Out Wafer-Level Packaging
- Table 20. Major Players of Flip Chip Wafer-Level Packaging
- Table 21. Major Players of 3D Integrated Circuit Packaging
- Table 22. Major Players of Others
- Table 23. Global Wafer-Level Underfill Sales by Package Type (2021-2026) & (Tons)
- Table 24. Global Wafer-Level Underfill Sales Market Share by Package Type (2021-2026)
- Table 25. Global Wafer-Level Underfill Revenue by Package Type (2021-2026) & (\$ million)
- Table 26. Global Wafer-Level Underfill Revenue Market Share by Package Type (2021-2026)
- Table 27. Global Wafer-Level Underfill Sale Price by Package Type (2021-2026) &

(US\$/kg)

Table 28. Major Players of Nano-Filled

Table 29. Major Players of Silica-Filled

Table 30. Major Players of Others

Table 31. Global Wafer-Level Underfill Sales by Filler Type (2021-2026) & (Tons)

Table 32. Global Wafer-Level Underfill Sales Market Share by Filler Type (2021-2026)

Table 33. Global Wafer-Level Underfill Revenue by Filler Type (2021-2026) & (\$ million)

Table 34. Global Wafer-Level Underfill Revenue Market Share by Filler Type (2021-2026)

Table 35. Global Wafer-Level Underfill Sale Price by Filler Type (2021-2026) & (US\$/kg)

Table 36. Global Wafer-Level Underfill Sale by Application (2021-2026) & (Tons)

Table 37. Global Wafer-Level Underfill Sale Market Share by Application (2021-2026)

Table 38. Global Wafer-Level Underfill Revenue by Application (2021-2026) & (\$ million)

Table 39. Global Wafer-Level Underfill Revenue Market Share by Application (2021-2026)

Table 40. Global Wafer-Level Underfill Sale Price by Application (2021-2026) & (US\$/kg)

Table 41. Global Wafer-Level Underfill Sales by Company (2021-2026) & (Tons)

Table 42. Global Wafer-Level Underfill Sales Market Share by Company (2021-2026)

Table 43. Global Wafer-Level Underfill Revenue by Company (2021-2026) & (\$ millions)

Table 44. Global Wafer-Level Underfill Revenue Market Share by Company (2021-2026)

Table 45. Global Wafer-Level Underfill Sale Price by Company (2021-2026) & (US\$/kg)

Table 46. Key Manufacturers Wafer-Level Underfill Producing Area Distribution and Sales Area

Table 47. Players Wafer-Level Underfill Products Offered

Table 48. Wafer-Level Underfill Concentration Ratio (CR3, CR5 and CR10) & (2024-2026)

Table 49. New Products and Potential Entrants

Table 50. Market M&A Activity & Strategy

Table 51. Global Wafer-Level Underfill Sales by Geographic Region (2021-2026) & (Tons)

Table 52. Global Wafer-Level Underfill Sales Market Share Geographic Region (2021-2026)

Table 53. Global Wafer-Level Underfill Revenue by Geographic Region (2021-2026) & (\$ millions)

Table 54. Global Wafer-Level Underfill Revenue Market Share by Geographic Region (2021-2026)

- Table 55. Global Wafer-Level Underfill Sales by Country/Region (2021-2026) & (Tons)
- Table 56. Global Wafer-Level Underfill Sales Market Share by Country/Region (2021-2026)
- Table 57. Global Wafer-Level Underfill Revenue by Country/Region (2021-2026) & (\$ millions)
- Table 58. Global Wafer-Level Underfill Revenue Market Share by Country/Region (2021-2026)
- Table 59. Americas Wafer-Level Underfill Sales by Country (2021-2026) & (Tons)
- Table 60. Americas Wafer-Level Underfill Sales Market Share by Country (2021-2026)
- Table 61. Americas Wafer-Level Underfill Revenue by Country (2021-2026) & (\$ millions)
- Table 62. Americas Wafer-Level Underfill Sales by Type (2021-2026) & (Tons)
- Table 63. Americas Wafer-Level Underfill Sales by Application (2021-2026) & (Tons)
- Table 64. APAC Wafer-Level Underfill Sales by Region (2021-2026) & (Tons)
- Table 65. APAC Wafer-Level Underfill Sales Market Share by Region (2021-2026)
- Table 66. APAC Wafer-Level Underfill Revenue by Region (2021-2026) & (\$ millions)
- Table 67. APAC Wafer-Level Underfill Sales by Type (2021-2026) & (Tons)
- Table 68. APAC Wafer-Level Underfill Sales by Application (2021-2026) & (Tons)
- Table 69. Europe Wafer-Level Underfill Sales by Country (2021-2026) & (Tons)
- Table 70. Europe Wafer-Level Underfill Revenue by Country (2021-2026) & (\$ millions)
- Table 71. Europe Wafer-Level Underfill Sales by Type (2021-2026) & (Tons)
- Table 72. Europe Wafer-Level Underfill Sales by Application (2021-2026) & (Tons)
- Table 73. Middle East & Africa Wafer-Level Underfill Sales by Country (2021-2026) & (Tons)
- Table 74. Middle East & Africa Wafer-Level Underfill Revenue Market Share by Country (2021-2026)
- Table 75. Middle East & Africa Wafer-Level Underfill Sales by Type (2021-2026) & (Tons)
- Table 76. Middle East & Africa Wafer-Level Underfill Sales by Application (2021-2026) & (Tons)
- Table 77. Key Market Drivers & Growth Opportunities of Wafer-Level Underfill
- Table 78. Key Market Challenges & Risks of Wafer-Level Underfill
- Table 79. Key Industry Trends of Wafer-Level Underfill
- Table 80. Wafer-Level Underfill Raw Material
- Table 81. Key Suppliers of Raw Materials
- Table 82. Wafer-Level Underfill Distributors List
- Table 83. Wafer-Level Underfill Customer List
- Table 84. Global Wafer-Level Underfill Sales Forecast by Region (2027-2032) & (Tons)
- Table 85. Global Wafer-Level Underfill Revenue Forecast by Region (2027-2032) & (\$

millions)

Table 86. Americas Wafer-Level Underfill Sales Forecast by Country (2027-2032) & (Tons)

Table 87. Americas Wafer-Level Underfill Annual Revenue Forecast by Country (2027-2032) & (\$ millions)

Table 88. APAC Wafer-Level Underfill Sales Forecast by Region (2027-2032) & (Tons)

Table 89. APAC Wafer-Level Underfill Annual Revenue Forecast by Region (2027-2032) & (\$ millions)

Table 90. Europe Wafer-Level Underfill Sales Forecast by Country (2027-2032) & (Tons)

Table 91. Europe Wafer-Level Underfill Revenue Forecast by Country (2027-2032) & (\$ millions)

Table 92. Middle East & Africa Wafer-Level Underfill Sales Forecast by Country (2027-2032) & (Tons)

Table 93. Middle East & Africa Wafer-Level Underfill Revenue Forecast by Country (2027-2032) & (\$ millions)

Table 94. Global Wafer-Level Underfill Sales Forecast by Type (2027-2032) & (Tons)

Table 95. Global Wafer-Level Underfill Revenue Forecast by Type (2027-2032) & (\$ millions)

Table 96. Global Wafer-Level Underfill Sales Forecast by Application (2027-2032) & (Tons)

Table 97. Global Wafer-Level Underfill Revenue Forecast by Application (2027-2032) & (\$ millions)

Table 98. Hubei Huitian New Materials Co., Ltd. Basic Information, Wafer-Level Underfill Manufacturing Base, Sales Area and Its Competitors

Table 99. Hubei Huitian New Materials Co., Ltd. Wafer-Level Underfill Product Portfolios and Specifications

Table 100. Hubei Huitian New Materials Co., Ltd. Wafer-Level Underfill Sales (Tons), Revenue (\$ Million), Price (US\$/kg) and Gross Margin (2021-2026)

Table 101. Hubei Huitian New Materials Co., Ltd. Main Business

Table 102. Hubei Huitian New Materials Co., Ltd. Latest Developments

Table 103. Darbond Technology Co., Ltd. Basic Information, Wafer-Level Underfill Manufacturing Base, Sales Area and Its Competitors

Table 104. Darbond Technology Co., Ltd. Wafer-Level Underfill Product Portfolios and Specifications

Table 105. Darbond Technology Co., Ltd. Wafer-Level Underfill Sales (Tons), Revenue (\$ Million), Price (US\$/kg) and Gross Margin (2021-2026)

Table 106. Darbond Technology Co., Ltd. Main Business

Table 107. Darbond Technology Co., Ltd. Latest Developments

Table 108. Jiangsu HHCK Advanced Materials Co., Ltd. Basic Information, Wafer-Level Underfill Manufacturing Base, Sales Area and Its Competitors

Table 109. Jiangsu HHCK Advanced Materials Co., Ltd. Wafer-Level Underfill Product Portfolios and Specifications

Table 110. Jiangsu HHCK Advanced Materials Co., Ltd. Wafer-Level Underfill Sales (Tons), Revenue (\$ Million), Price (US\$/kg) and Gross Margin (2021-2026)

Table 111. Jiangsu HHCK Advanced Materials Co., Ltd. Main Business

Table 112. Jiangsu HHCK Advanced Materials Co., Ltd. Latest Developments

Table 113. Henkel AG & Co. KGaA Basic Information, Wafer-Level Underfill Manufacturing Base, Sales Area and Its Competitors

Table 114. Henkel AG & Co. KGaA Wafer-Level Underfill Product Portfolios and Specifications

Table 115. Henkel AG & Co. KGaA Wafer-Level Underfill Sales (Tons), Revenue (\$ Million), Price (US\$/kg) and Gross Margin (2021-2026)

Table 116. Henkel AG & Co. KGaA Main Business

Table 117. Henkel AG & Co. KGaA Latest Developments

Table 118. Element Solutions Inc Basic Information, Wafer-Level Underfill Manufacturing Base, Sales Area and Its Competitors

Table 119. Element Solutions Inc Wafer-Level Underfill Product Portfolios and Specifications

Table 120. Element Solutions Inc Wafer-Level Underfill Sales (Tons), Revenue (\$ Million), Price (US\$/kg) and Gross Margin (2021-2026)

Table 121. Element Solutions Inc Main Business

Table 122. Element Solutions Inc Latest Developments

Table 123. NAMICS Corporation Basic Information, Wafer-Level Underfill Manufacturing Base, Sales Area and Its Competitors

Table 124. NAMICS Corporation Wafer-Level Underfill Product Portfolios and Specifications

Table 125. NAMICS Corporation Wafer-Level Underfill Sales (Tons), Revenue (\$ Million), Price (US\$/kg) and Gross Margin (2021-2026)

Table 126. NAMICS Corporation Main Business

Table 127. NAMICS Corporation Latest Developments

Table 128. Resonac Corporation Basic Information, Wafer-Level Underfill Manufacturing Base, Sales Area and Its Competitors

Table 129. Resonac Corporation Wafer-Level Underfill Product Portfolios and Specifications

Table 130. Resonac Corporation Wafer-Level Underfill Sales (Tons), Revenue (\$ Million), Price (US\$/kg) and Gross Margin (2021-2026)

Table 131. Resonac Corporation Main Business

- Table 132. Resonac Corporation Latest Developments
- Table 133. H.B. Fuller Company Basic Information, Wafer-Level Underfill Manufacturing Base, Sales Area and Its Competitors
- Table 134. H.B. Fuller Company Wafer-Level Underfill Product Portfolios and Specifications
- Table 135. H.B. Fuller Company Wafer-Level Underfill Sales (Tons), Revenue (\$ Million), Price (US\$/kg) and Gross Margin (2021-2026)
- Table 136. H.B. Fuller Company Main Business
- Table 137. H.B. Fuller Company Latest Developments
- Table 138. Hoenle AG Basic Information, Wafer-Level Underfill Manufacturing Base, Sales Area and Its Competitors
- Table 139. Hoenle AG Wafer-Level Underfill Product Portfolios and Specifications
- Table 140. Hoenle AG Wafer-Level Underfill Sales (Tons), Revenue (\$ Million), Price (US\$/kg) and Gross Margin (2021-2026)
- Table 141. Hoenle AG Main Business
- Table 142. Hoenle AG Latest Developments
- Table 143. Zymet, Inc. Basic Information, Wafer-Level Underfill Manufacturing Base, Sales Area and Its Competitors
- Table 144. Zymet, Inc. Wafer-Level Underfill Product Portfolios and Specifications
- Table 145. Zymet, Inc. Wafer-Level Underfill Sales (Tons), Revenue (\$ Million), Price (US\$/kg) and Gross Margin (2021-2026)
- Table 146. Zymet, Inc. Main Business
- Table 147. Zymet, Inc. Latest Developments
- Table 148. Dexerials Corporation Basic Information, Wafer-Level Underfill Manufacturing Base, Sales Area and Its Competitors
- Table 149. Dexerials Corporation Wafer-Level Underfill Product Portfolios and Specifications
- Table 150. Dexerials Corporation Wafer-Level Underfill Sales (Tons), Revenue (\$ Million), Price (US\$/kg) and Gross Margin (2021-2026)
- Table 151. Dexerials Corporation Main Business
- Table 152. Dexerials Corporation Latest Developments
- Table 153. Shin-Etsu Chemical Co., Ltd. Basic Information, Wafer-Level Underfill Manufacturing Base, Sales Area and Its Competitors
- Table 154. Shin-Etsu Chemical Co., Ltd. Wafer-Level Underfill Product Portfolios and Specifications
- Table 155. Shin-Etsu Chemical Co., Ltd. Wafer-Level Underfill Sales (Tons), Revenue (\$ Million), Price (US\$/kg) and Gross Margin (2021-2026)
- Table 156. Shin-Etsu Chemical Co., Ltd. Main Business
- Table 157. Shin-Etsu Chemical Co., Ltd. Latest Developments

List Of Figures

LIST OF FIGURES

- Figure 1. Picture of Wafer-Level Underfill
- Figure 2. Wafer-Level Underfill Report Years Considered
- Figure 3. Research Objectives
- Figure 4. Research Methodology
- Figure 5. Research Process and Data Source
- Figure 6. Global Wafer-Level Underfill Sales Growth Rate 2021-2032 (Tons)
- Figure 7. Global Wafer-Level Underfill Revenue Growth Rate 2021-2032 (\$ millions)
- Figure 8. Wafer-Level Underfill Sales by Geographic Region (2021, 2025 & 2032) & (\$ millions)
- Figure 9. Wafer-Level Underfill Sales Market Share by Country/Region (2025)
- Figure 10. Wafer-Level Underfill Sales Market Share by Country/Region (2021, 2025 & 2032)
- Figure 11. Product Picture of Liquid Underfill
- Figure 12. Product Picture of Paste Underfill
- Figure 13. Product Picture of Film Underfill
- Figure 14. Global Wafer-Level Underfill Sales Market Share by Type in 2026
- Figure 15. Global Wafer-Level Underfill Revenue Market Share by Type (2021-2026)
- Figure 16. Product Picture of Standard Thermal Cure
- Figure 17. Product Picture of Fast Thermal Cure
- Figure 18. Product Picture of Low Temperature Cure
- Figure 19. Global Wafer-Level Underfill Sales Market Share by Cure Profile in 2026
- Figure 20. Global Wafer-Level Underfill Revenue Market Share by Cure Profile (2021-2026)
- Figure 21. Product Picture of Fan-Out Wafer-Level Packaging
- Figure 22. Product Picture of Flip Chip Wafer-Level Packaging
- Figure 23. Product Picture of 3D Integrated Circuit Packaging
- Figure 24. Product Picture of Others
- Figure 25. Global Wafer-Level Underfill Sales Market Share by Package Type in 2026
- Figure 26. Global Wafer-Level Underfill Revenue Market Share by Package Type (2021-2026)
- Figure 27. Product Picture of Nano-Filled
- Figure 28. Product Picture of Silica-Filled
- Figure 29. Product Picture of Others
- Figure 30. Global Wafer-Level Underfill Sales Market Share by Filler Type in 2026
- Figure 31. Global Wafer-Level Underfill Revenue Market Share by Filler Type

(2021-2026)

Figure 32. Wafer-Level Underfill Consumed in Consumer Electronics

Figure 33. Global Wafer-Level Underfill Market: Consumer Electronics (2021-2026) & (Tons)

Figure 34. Wafer-Level Underfill Consumed in Data Center and Communications

Figure 35. Global Wafer-Level Underfill Market: Data Center and Communications (2021-2026) & (Tons)

Figure 36. Wafer-Level Underfill Consumed in Automotive Electronics

Figure 37. Global Wafer-Level Underfill Market: Automotive Electronics (2021-2026) & (Tons)

Figure 38. Wafer-Level Underfill Consumed in Others

Figure 39. Global Wafer-Level Underfill Market: Others (2021-2026) & (Tons)

Figure 40. Global Wafer-Level Underfill Sales Market Share by Application (2025)

Figure 41. Global Wafer-Level Underfill Revenue Market Share by Application in 2025

Figure 42. Wafer-Level Underfill Sales by Company in 2025 (Tons)

Figure 43. Global Wafer-Level Underfill Sales Market Share by Company in 2025

Figure 44. Wafer-Level Underfill Revenue by Company in 2025 (\$ millions)

Figure 45. Global Wafer-Level Underfill Revenue Market Share by Company in 2025

Figure 46. Global Wafer-Level Underfill Sales Market Share by Geographic Region (2021-2026)

Figure 47. Global Wafer-Level Underfill Revenue Market Share by Geographic Region in 2025

Figure 48. Americas Wafer-Level Underfill Sales 2021-2026 (Tons)

Figure 49. Americas Wafer-Level Underfill Revenue 2021-2026 (\$ millions)

Figure 50. APAC Wafer-Level Underfill Sales 2021-2026 (Tons)

Figure 51. APAC Wafer-Level Underfill Revenue 2021-2026 (\$ millions)

Figure 52. Europe Wafer-Level Underfill Sales 2021-2026 (Tons)

Figure 53. Europe Wafer-Level Underfill Revenue 2021-2026 (\$ millions)

Figure 54. Middle East & Africa Wafer-Level Underfill Sales 2021-2026 (Tons)

Figure 55. Middle East & Africa Wafer-Level Underfill Revenue 2021-2026 (\$ millions)

Figure 56. Americas Wafer-Level Underfill Sales Market Share by Country in 2025

Figure 57. Americas Wafer-Level Underfill Revenue Market Share by Country (2021-2026)

Figure 58. Americas Wafer-Level Underfill Sales Market Share by Type (2021-2026)

Figure 59. Americas Wafer-Level Underfill Sales Market Share by Application (2021-2026)

Figure 60. United States Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)

Figure 61. Canada Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)

Figure 62. Mexico Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)

- Figure 63. Brazil Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 64. APAC Wafer-Level Underfill Sales Market Share by Region in 2025
- Figure 65. APAC Wafer-Level Underfill Revenue Market Share by Region (2021-2026)
- Figure 66. APAC Wafer-Level Underfill Sales Market Share by Type (2021-2026)
- Figure 67. APAC Wafer-Level Underfill Sales Market Share by Application (2021-2026)
- Figure 68. China Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 69. Japan Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 70. South Korea Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 71. Southeast Asia Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 72. India Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 73. Australia Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 74. China Taiwan Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 75. Europe Wafer-Level Underfill Sales Market Share by Country in 2025
- Figure 76. Europe Wafer-Level Underfill Revenue Market Share by Country (2021-2026)
- Figure 77. Europe Wafer-Level Underfill Sales Market Share by Type (2021-2026)
- Figure 78. Europe Wafer-Level Underfill Sales Market Share by Application (2021-2026)
- Figure 79. Germany Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 80. France Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 81. UK Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 82. Italy Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 83. Russia Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 84. Middle East & Africa Wafer-Level Underfill Sales Market Share by Country (2021-2026)
- Figure 85. Middle East & Africa Wafer-Level Underfill Sales Market Share by Type (2021-2026)
- Figure 86. Middle East & Africa Wafer-Level Underfill Sales Market Share by Application (2021-2026)
- Figure 87. Egypt Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 88. South Africa Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 89. Israel Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 90. Turkey Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 91. GCC Countries Wafer-Level Underfill Revenue Growth 2021-2026 (\$ millions)
- Figure 92. Manufacturing Cost Structure Analysis of Wafer-Level Underfill in 2026
- Figure 93. Manufacturing Process Analysis of Wafer-Level Underfill
- Figure 94. Industry Chain Structure of Wafer-Level Underfill
- Figure 95. Channels of Distribution

Figure 96. Global Wafer-Level Underfill Sales Market Forecast by Region (2027-2032)

Figure 97. Global Wafer-Level Underfill Revenue Market Share Forecast by Region (2027-2032)

Figure 98. Global Wafer-Level Underfill Sales Market Share Forecast by Type (2027-2032)

Figure 99. Global Wafer-Level Underfill Revenue Market Share Forecast by Type (2027-2032)

Figure 100. Global Wafer-Level Underfill Sales Market Share Forecast by Application (2027-2032)

Figure 101. Global Wafer-Level Underfill Revenue Market Share Forecast by Application (2027-2032)

I would like to order

Product name: Global Wafer-Level Underfill Market Growth 2026-2032

Product link: <https://marketpublishers.com/r/GB3A6C03420EEN.html>

Price: US\$ 3,660.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/GB3A6C03420EEN.html>